

LM723JAN Voltage Regulator

Check for Samples: [LM723JAN](#)

FEATURES

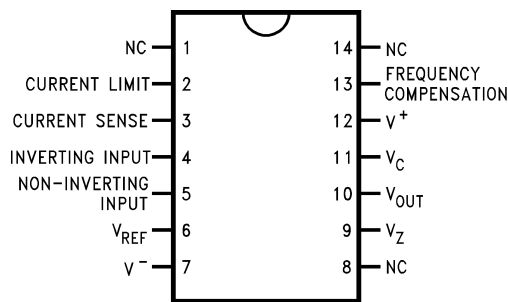
- **150 mA Output Current without External Pass Transistor**
- **Output Currents in Excess of 10A Possible by Adding External Transistors**
- **Input Voltage 40V Max**
- **Output Voltage Adjustable from 2V to 37V**
- **Can be Used as Either a Linear or a Switching Regulator**

DESCRIPTION

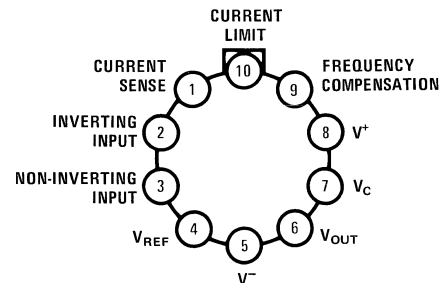
The LM723 is a voltage regulator designed primarily for series regulator applications. By itself, it will supply output currents up to 150 mA; but external transistors can be added to provide any desired load current. The circuit features extremely low standby current drain, and provision is made for either linear or foldback current limiting.

The LM723 is also useful in a wide range of other applications such as a shunt regulator, a current regulator or a temperature controller.

Connection Diagram



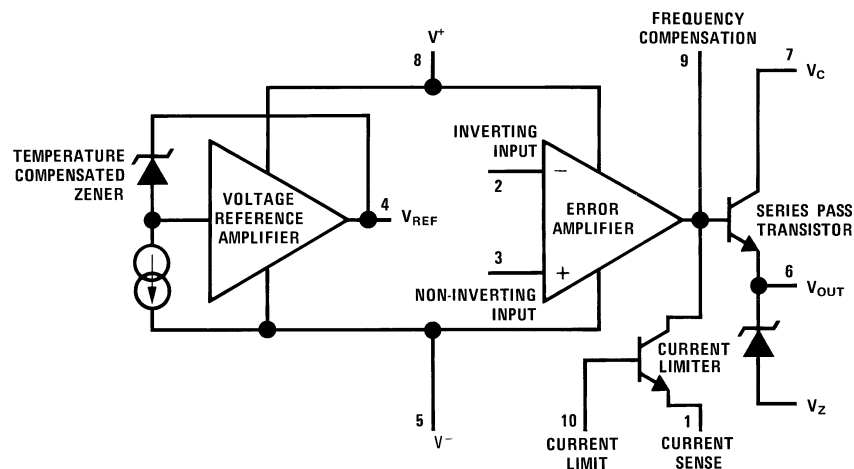
**Figure 1. CDIP Package
Top View
See Package J0014A**



NOTE: Pin 5 connected to case.

**Figure 2. Metal Can Package
Top View
See Package LME0010C**

Equivalent Circuit



Pin numbers refer to metal can package.



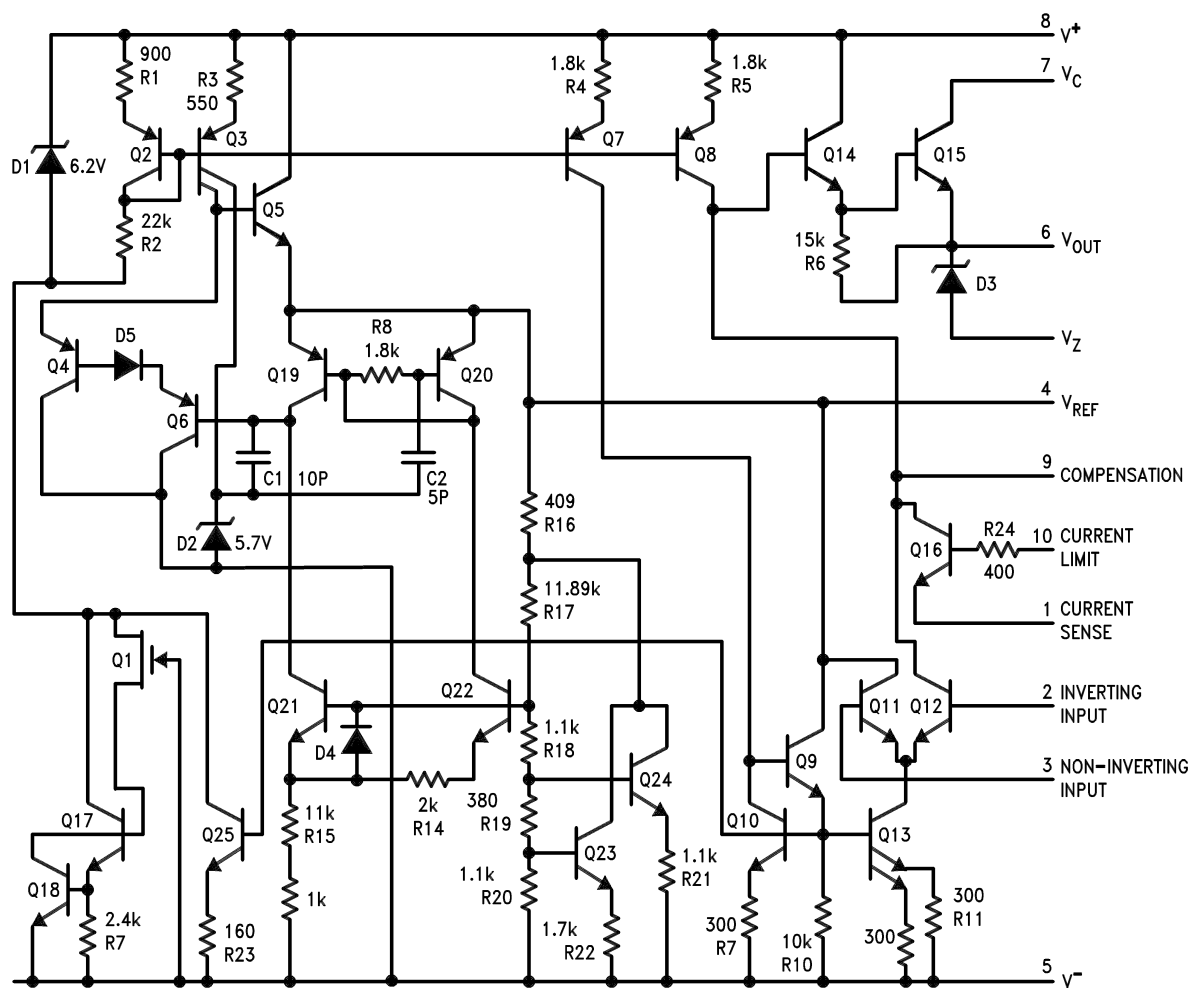
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Schematic Diagram





These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings⁽¹⁾

Pulse Voltage from V^+ to V^- (50 ms)		50V
Continuous Voltage from V^+ to V^-		40V
Input-Output Voltage Differential		40V
Differential Input Voltage		$\pm 5V$
Voltage between non-inverting input and V^-		+8V
Current from V_Z		25 mA
Current from V_{REF}		15 mA
Internal Power Dissipation ($T_A = 125^\circ C$)	Metal Can ⁽²⁾	300 mW
	CDIP ⁽²⁾	400 mW
Maximum T_J		+175°C
Storage Temperature Range		$-65^\circ C \leq T_A \leq +150^\circ C$
Lead Temperature (Soldering, 4 sec. max.)		300°C
Thermal Resistance		
θ_{JA}	CDIP (Still Air)	100°C/W
	CDIP (500LF/ Min Air flow)	61°C/W
	Metal Can (Still Air)	156°C/W
	Metal Can (500LF/ Min Air flow)	89°C/W
θ_{JC}	CDIP	22°C/W
	Metal Can	37°C/W
ESD Tolerance ⁽³⁾		1200V

- (1) "Absolute Maximum Ratings" indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not ensure specific performance limits. For ensured specifications and test conditions, see the Electrical Characteristics. The ensured specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.
- (2) The maximum power dissipation for these devices must be derated at elevated temperatures and is dictated by T_{JMAX} , θ_{JA} , and the ambient temperature, T_A . The maximum available power dissipation at any temperature is $P_d = (T_{JMAX} - T_A)/\theta_{JA}$ or the number given in the Absolute Maximum Ratings, whichever is less. See derating curves for maximum power rating above 25°C.
- (3) Human body model, 1.5 k Ω in series with 100 pF.

Recommended Operating Conditions

Input Voltage Range	9.5V to 40V _{DC}
Output Voltage Range	2V to 37V _{DC}
Input-Output Voltage Differential	2.5 V to 38V _{DC}
Ambient Operating Temperature Range	$-55^\circ C \leq T_A \leq +125^\circ C$

Quality Conformance Inspection

MIL-STD-883, Method 5004 and Method 5005

Subgroup	Description	Temp (°C)
1	Static tests at	+25
2	Static tests at	+125
3	Static tests at	-55
4	Dynamic tests at	+25
5	Dynamic tests at	+125
6	Dynamic tests at	-55
7	Functional tests at	+25
8A	Functional tests at	+125
8B	Functional tests at	-55

Subgroup	Description	Temp (°C)
9	Switching tests at	+25
10	Switching tests at	+125
11	Switching tests at	-55

Electrical Characteristics

DC Parameters ⁽¹⁾

Symbol	Parameter	Conditions	Notes	Min	Max	Units	Sub-groups
V_{Rline}	Line Regulation	$12V \leq V_{IN} \leq 15V$, $V_{OUT} = 5V$, $I_L = 1mA$		-0.1	0.1	% V_{OUT}	1
				-0.2	0.2	% V_{OUT}	2
				-0.3	0.3	% V_{OUT}	3
		$12V \leq V_{IN} \leq 40V$, $V_{OUT} = 2V$, $I_L = 1mA$		-0.2	0.2	% V_{OUT}	1
		$9.5V \leq V_{IN} \leq 40V$, $V_{OUT} = 5V$, $I_L = 1mA$		-0.3	0.3	% V_{OUT}	1
		$12V \leq V_{IN} \leq 15V$, $V_{OUT} = 5V$, $I_L = 1mA$		-10. 0	+10. 0	mV	1
				-20. 0	+20. 0	mV	2
				-30. 0	+30. 0	mV	3
V_{Rload}	Load Regulation	$1mA \leq I_L \leq 50mA$, $V_{IN} = 12V$, $V_{OUT} = 5V$		-0.1 5	0.15	% V_{OUT}	1
				-0.4	0.4	% V_{OUT}	2
				-0.6	0.6	% V_{OUT}	3
		$1mA \leq I_L \leq 10mA$, $V_{IN} = 40V$, $V_{OUT} = 37V$		-0.5	0.5	% V_{OUT}	1
		$6mA \leq I_L \leq 12mA$, $V_{IN} = 10V$, $V_{OUT} = 7.5V$		-0.2	0.2	% V_{OUT}	1
		$1mA \leq I_L \leq 50mA$, $V_{IN} = 12V$, $V_{OUT} = 5V$		-15. 0	+15. 0	mV	1
				-40. 0	+40. 0	mV	2
				-60. 0	+60. 0	mV	3
V_{REF}	Voltage Reference	$I_{REF} = 1mA$, $V_{IN} = 12V$		6.95	7.35	V	1
				6.9	7.4	V	2, 3
I_{SCD}	Standby Current	$V_{IN} = 30V$, $I_L = I_{REF} = 0$, $V_{OUT} = V_{REF}$		0.5	3	mA	1
				0.5	2.4	mA	2
				0.5	3.5	mA	3
I_{OS}	Short Circuit Current	$V_{OUT} = 5V$, $V_{IN} = 12V$, $R_{SC} = 10\Omega$, $R_L = 0$		45	85	mA	1
V_Z	Zener Voltage	$I_Z = 1mA$		(2)(3) 5.58	6.82	V	1
V_{OUT}	Output Voltage	$V_{IN} = 12V$, $V_{OUT} = 5V$, $I_L = 1mA$	(4)	4.5	5.5	V	1, 2, 3

(1) Unless otherwise specified, $T_A = 25^\circ C$, $V_{IN} = V^+ = V_C = 12V$, $V^- = 0$, $V_{OUT} = 5V$, $I_L = 1mA$, $R_{SC} = 0$, $C_1 = 100pF$, $C_{REF} = 0$ and divider impedance as seen by error amplifier $\leq 10k\Omega$ connected as shown in [Figure 14](#). Line and load regulation specifications are given for the condition of constant chip temperature. Temperature drifts must be taken into account separately for high dissipation conditions.

(2) For metal can applications where V_Z is required, an external 6.2V zener diode should be connected in series with V_{OUT} .

(3) Tested for 14 – lead DIP only.

(4) Setup test for Temp. Coeff.

Electrical Characteristics (continued)

DC Parameters ⁽¹⁾

Symbol	Parameter	Conditions	Notes	Min	Max	Units	Sub-groups
Delta V_{OUT} / Delta T	Average Temperature Coefficient of Output Voltage	$25^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$, $V_{IN} = 12\text{V}$, $V_{OUT} = 5\text{V}$, $I_L = 1\text{mA}$	(5)	-0.0	0.01	%/ $^{\circ}\text{C}$	8A
		$-55^{\circ}\text{C} \leq T_A \leq +25^{\circ}\text{C}$, $V_{IN} = 12\text{V}$, $V_{OUT} = 5\text{V}$, $I_L = 1\text{mA}$	(5)	-0.0	0.01	%/ $^{\circ}\text{C}$	8B
Delta V_{OUT} / Delta V_{IN}	Ripple Rejection	$f = 10\text{KHz}$, $C_{REF} = 0\text{F}$, $V_{INS} = 2V_{RMS}$		64		dB	4
		$f = 10\text{KHz}$, $C_{REF} = 5\mu\text{F}$, $V_{INS} = 2V_{RMS}$		76		dB	4
N_O	Output Noise Voltage	$100\text{Hz} \leq f \leq 10\text{KHz}$, $V_{INS} = 0V_{RMS}$, $C_{REF} = 0\mu\text{F}$			120	μV_{RMS}	4
		$100\text{Hz} \leq f \leq 10\text{KHz}$, $V_{INS} = 0V_{RMS}$, $C_{REF} = 5\mu\text{F}$			7	μV_{RMS}	4
Delta V_{OUT} / Delta V_{IN}	Line Transient Response	$V_{IN} = 12\text{V}$, $V_{OUT} = 5\text{V}$, $I_L = 1\text{mA}$, $C_{REF} = 5\mu\text{F}$, $R_{SC} = 0\Omega$, Delta $V_{IN} = 3\text{V}$ for $25\mu\text{sec}$		0	10	mV/V	4
Delta V_{OUT} / Delta I_L	Load Transient Response	$V_{IN} = 12\text{V}$, $V_{OUT} = 5\text{V}$, $I_L = 40\text{mA}$, $C_{REF} = 5\mu\text{F}$, $R_{SC} = 0\Omega$, Delta $I_L = 10\text{mA}$ for $25\mu\text{sec}$		-1.5	0	mV/mA	4

(5) Calculated parameter

DC Parameters: Drift Values

Delta calculations performed on JAN S and QMLV devices at Group B, Subgroup 5, only.

Symbol	Parameters	Conditions	Notes	Min	Max	Unit	Sub-groups
V_{Rline}	Line Regulation	$12\text{V} \leq V_{IN} \leq 15\text{V}$, $V_{OUT} = 5\text{V}$, $I_L = 1\text{mA}$, $\pm 1\text{mV}$, or $\pm 15\%$ (whichever is greater)		-1.0	1.0	mV	1
V_{Rload}	Load Regulation	$1\text{mA} \leq I_L \leq 50\text{mA}$, $V_{IN} = 12\text{V}$, $V_{OUT} = 5\text{V}$, $\pm 1\text{mV}$, or $\pm 20\%$ (whichever is greater)		-1.0	1.0	mV	1
V_{REF}	Reference Voltage	$I_{REF} = 1\text{mA}$, $V_{IN} = 12\text{V}$		-15	15	mV	1
I_{SCD}	Standby Current Drain	$V_{IN} = 30\text{V}$, $I_L = I_{REF} = 0$, $V_{OUT} = V_{REF}$		-10	10	%	1

Typical Performance Characteristics

Load Regulation Characteristics with Current Limiting

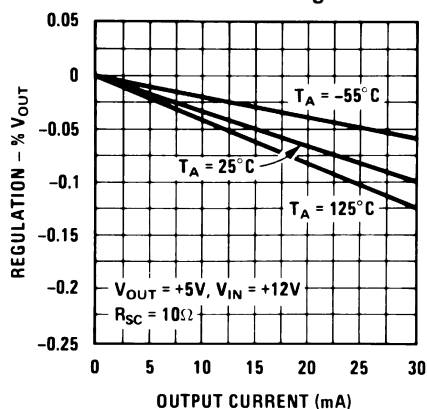


Figure 3.

Load Regulation Characteristics with Current Limiting

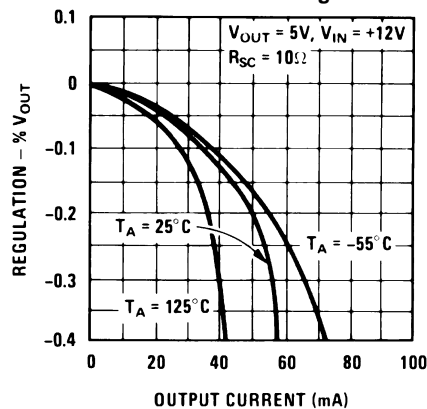


Figure 4.

Load & Line Regulation vs Input-Output Voltage Differential

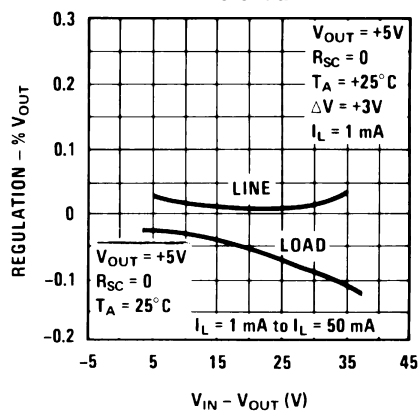


Figure 5.

Current Limiting Characteristics

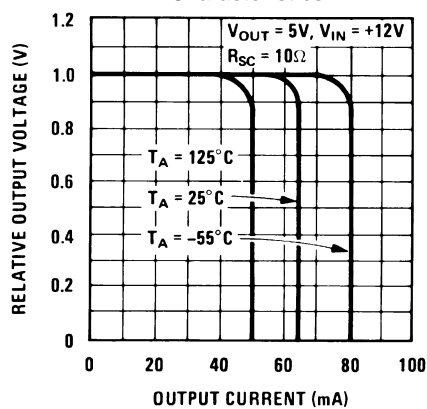


Figure 6.

Current Limiting Characteristics vs Junction Temperature

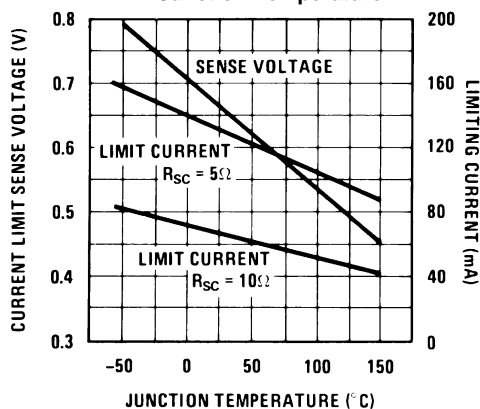


Figure 7.

Standby Current Drain vs Input Voltage

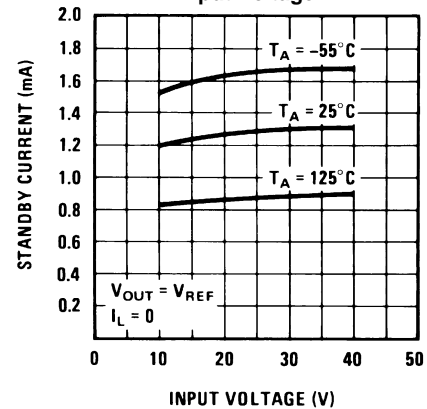


Figure 8.

Typical Performance Characteristics (continued)

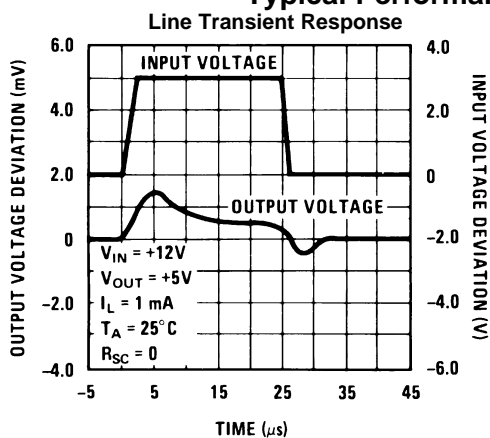


Figure 9.

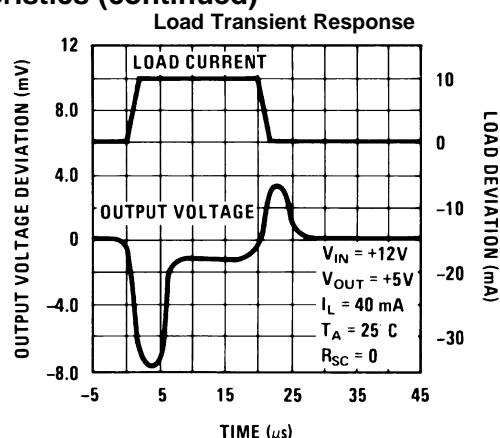


Figure 10.

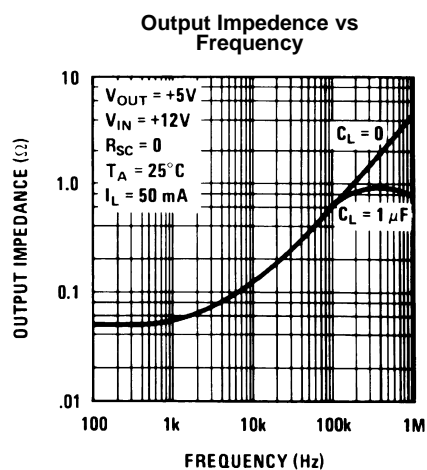


Figure 11.

Maximum Power Ratings

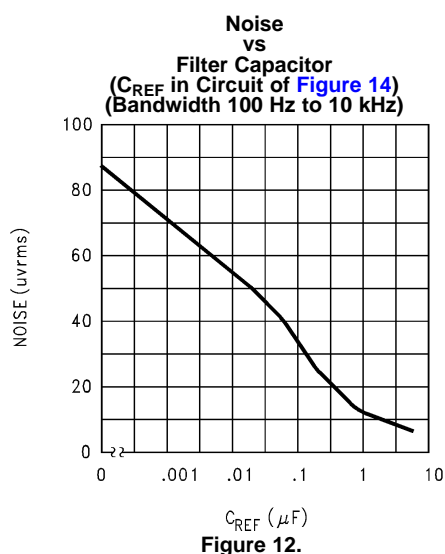


Figure 12.

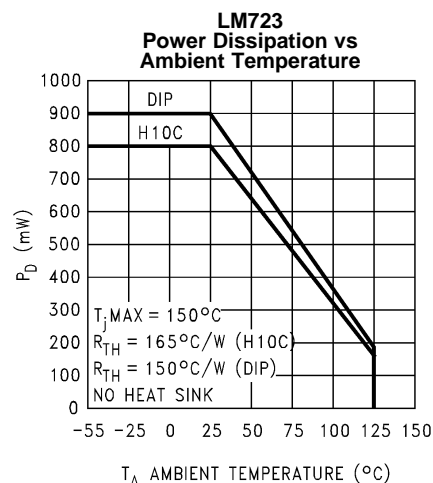


Figure 13.

Table 1. Resistor Values (kΩ) for Standard Output Voltage

Positive Output Voltage	Applicable Figures ⁽¹⁾	Fixed Output ±5%		Output Adjustable ±10% ⁽²⁾			Negative Output Voltage	Applicable Figures	Fixed Output ±5%		5% Output Adjustable ±10%		
		R1	R2	R1	P1	R2			R1	R2	R1	P1	R2
+3.0	Figure 14, Figure 18, Figure 19, Figure 22, Figure 25 (Figure 17)	4.12	3.01	1.8	0.5	1.2	+100	Figure 20	3.57	102	2.2	10	91
+3.6	Figure 14, Figure 18, Figure 19, Figure 22, Figure 25 (Figure 17)	3.57	3.65	1.5	0.5	1.5	+250	Figure 20	3.57	255	2.2	10	240
+5.0	Figure 14, Figure 18, Figure 19, Figure 22, Figure 25 (Figure 17)	2.15	4.99	0.75	0.5	2.2	−6 ⁽³⁾	Figure 16, (Figure 23)	3.57	2.43	1.2	0.5	0.75
+6.0	Figure 14, Figure 18, Figure 19, Figure 22, Figure 25 (Figure 17)	1.15	6.04	0.5	0.5	2.7	−9	Figure 16, Figure 23	3.48	5.36	1.2	0.5	2.0
+9.0	Figure 15, Figure 17, (Figure 18, Figure 19, Figure 22, Figure 25)	1.87	7.15	0.75	1.0	2.7	−12	Figure 16, Figure 23	3.57	8.45	1.2	0.5	3.3
+12	Figure 15, Figure 17, (Figure 18, Figure 19, Figure 22, Figure 25)	4.87	7.15	2.0	1.0	3.0	−15	Figure 16, Figure 23	3.65	11.5	1.2	0.5	4.3
+15	Figure 15, Figure 17, (Figure 18, Figure 19, Figure 22, Figure 25)	7.87	7.15	3.3	1.0	3.0	−28	Figure 16, Figure 23	3.57	24.3	1.2	0.5	10
+28	Figure 15, Figure 17, (Figure 18, Figure 19, Figure 22, Figure 25)	21.0	7.15	5.6	1.0	2.0	−45	Figure 21	3.57	41.2	2.2	10	33
+45	Figure 20	3.57	48.7	2.2	10	39	−100	Figure 21	3.57	97.6	2.2	10	91
+75	Figure 20	3.57	78.7	2.2	10	68	−250	Figure 21	3.57	249	2.2	10	240

(1) Figures in parentheses may be used if R1/R2 divider is placed on opposite input of error amp.

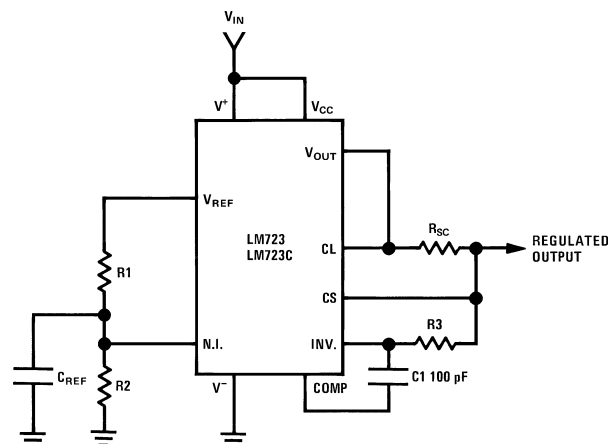
(2) Replace R1/R2 in figures with divider shown in Figure 26.

(3) V⁺ and V_{CC} must be connected to a +3V or greater supply.

Table 2. Formulae for Intermediate Output Voltages

Outputs from +2 to +7 volts	Outputs from +4 to +250 volts	Current Limiting
(Figure 14, Figure 17, Figure 18, Figure 19, Figure 22, Figure 25)	(Figure 20)	
$V_{OUT} = \left(V_{REF} \times \frac{R2}{R1 + R2} \right)$	$V_{OUT} = \left(\frac{V_{REF}}{2} \times \frac{R2 - R1}{R1} \right); R3 = R4$	$I_{LIMIT} = \frac{V_{SENSE}}{R_{SC}}$
Outputs from +7 to +37 volts	Outputs from −6 to −250 volts	Foldback Current Limiting
(Figure 15, Figure 17, Figure 18, Figure 19, Figure 22, Figure 25)	(Figure 16, Figure 21, Figure 23)	
$V_{OUT} = \left(V_{REF} \times \frac{R1 + R2}{R2} \right)$	$V_{OUT} = \left(\frac{V_{REF}}{2} \times \frac{R1 + R2}{R1} \right); R3 = R4$	$I_{KNEE} = \left(\frac{V_{OUT} R3}{R_{SC} R4} + \frac{V_{SENSE} (R3 + R4)}{R_{SC} R4} \right)$ $I_{SHORT\ CKT} = \left(\frac{V_{SENSE}}{R_{SC}} \times \frac{R3 + R4}{R4} \right)$

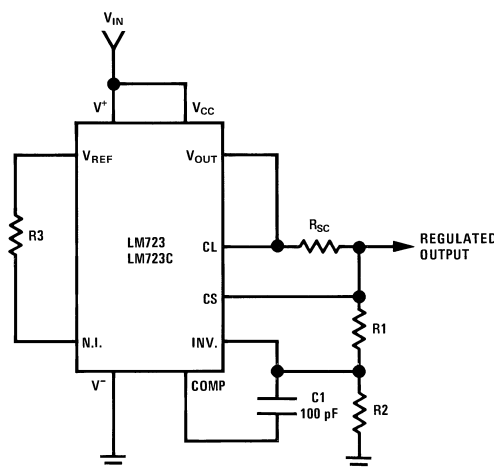
TYPICAL APPLICATIONS



Note: $R_3 = \frac{R_1 R_2}{R_1 + R_2}$ for minimum temperature drift

Figure 14. Basic Low Voltage Regulator ($V_{OUT} = 2$ to 7 Volts)

Typical Performance	
Regulated Output Voltage	5V
Line Regulation ($\Delta V_{IN} = 3V$)	0.5mV
Load Regulation ($\Delta I_L = 50$ mA)	1.5mV



Note: $R_3 = \frac{R_1 R_2}{R_1 + R_2}$ for minimum temperature drift.

R_3 may be eliminated for minimum component count.

Figure 15. Basic High Voltage Regulator ($V_{OUT} = 7$ to 37 Volts)

Typical Performance	
Regulated Output Voltage	15V
Line Regulation ($\Delta V_{IN} = 3V$)	1.5 mV
Load Regulation ($\Delta I_L = 50$ mA)	4.5 mV

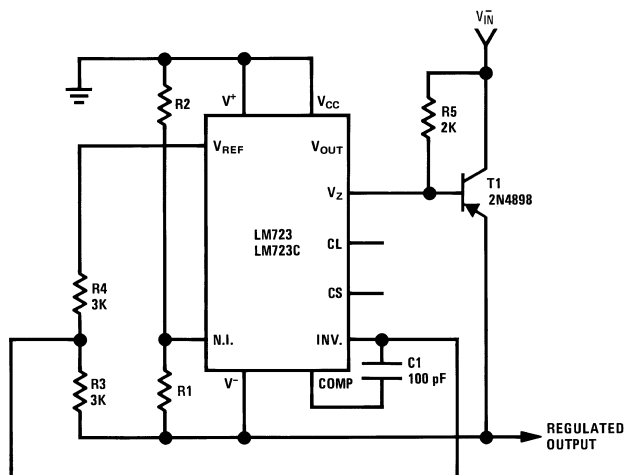


Figure 16. Negative Voltage Regulator

Typical Performance	
Regulated Output Voltage	-15V
Line Regulation ($\Delta V_{IN} = 3V$)	1 mV
Load Regulation ($\Delta I_L = 100 \text{ mA}$)	2 mV

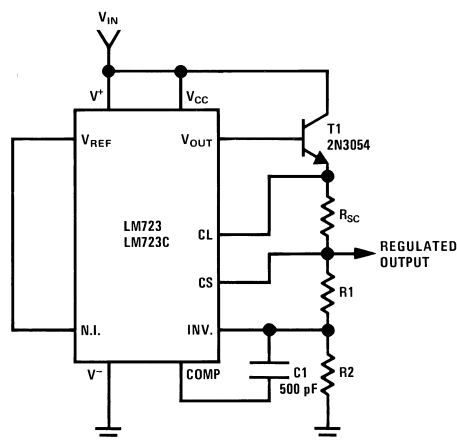


Figure 17. Positive Voltage Regulator (External NPN Pass Transistor)

Typical Performance	
Regulated Output Voltage	+15V
Line Regulation ($\Delta V_{IN} = 3V$)	1.5 mV
Load Regulation ($\Delta I_L = 1A$)	15 mV

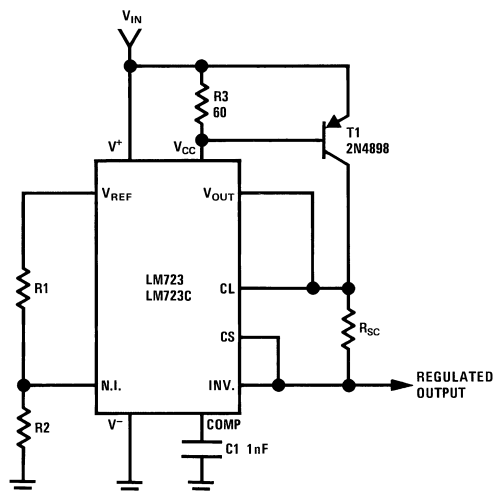


Figure 18. Positive Voltage Regulator (External PNP Pass Transistor)

Typical Performance	
Regulated Output Voltage	+5V
Line Regulation ($\Delta V_{IN} = 3V$)	0.5 mV
Load Regulation ($\Delta I_L = 1A$)	5 mV

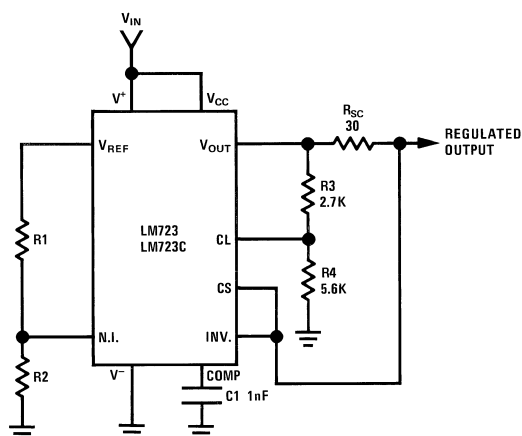


Figure 19. Foldback Current Limiting

Typical Performance	
Regulated Output Voltage	+5V
Line Regulation ($\Delta V_{IN} = 3V$)	0.5 mV
Load Regulation ($\Delta I_L = 10 \text{ mA}$)	1 mV
Short Circuit Current	20 mA

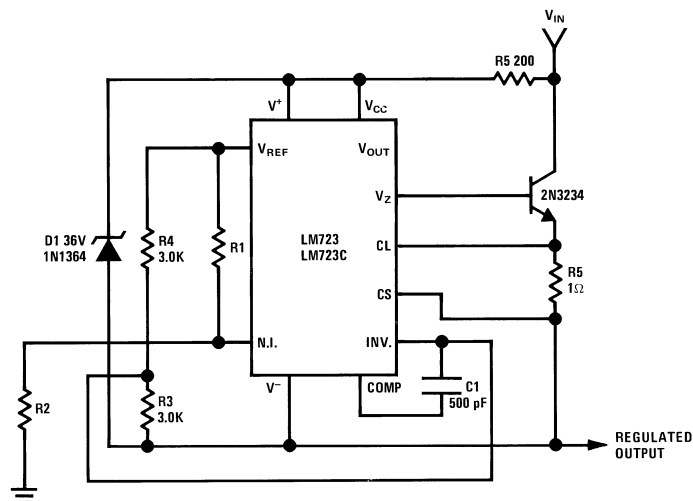


Figure 20. Positive Floating Regulator

Typical Performance	
Regulated Output Voltage	+50V
Line Regulation ($\Delta V_{IN} = 20V$)	15 mV
Load Regulation ($\Delta I_L = 50 \text{ mA}$)	20 mV

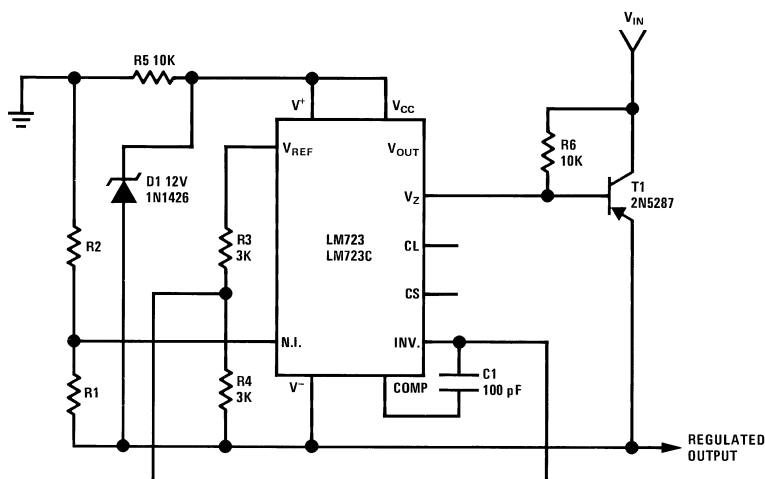
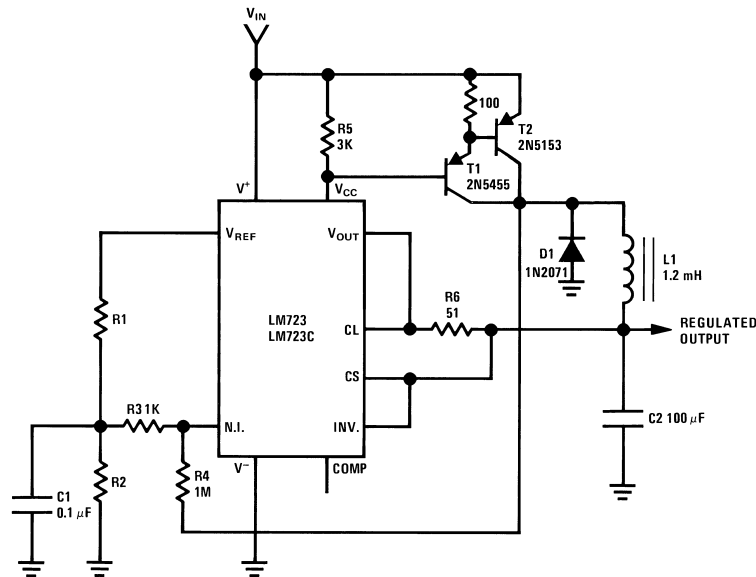


Figure 21. Negative Floating Regulator

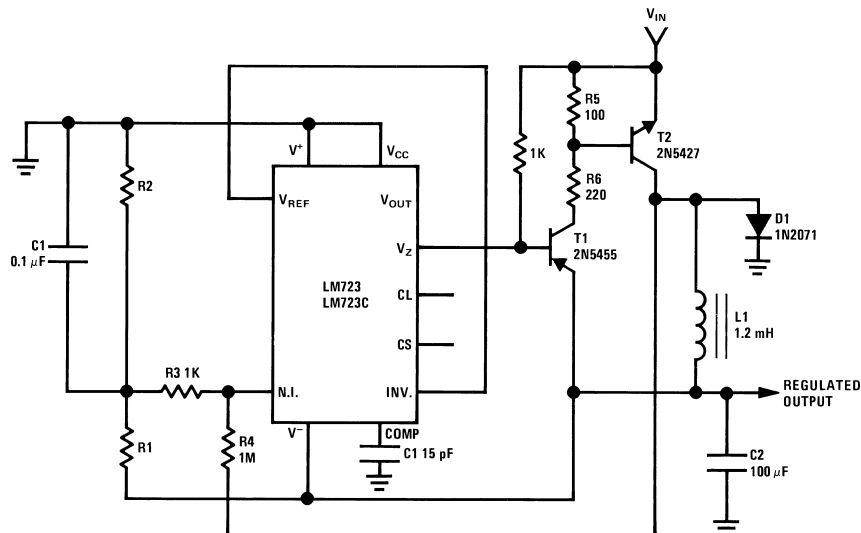
Typical Performance	
Regulated Output Voltage	-100V
Line Regulation ($\Delta V_{IN} = 20V$)	30 mV
Load Regulation ($\Delta I_L = 100 \text{ mA}$)	20 mV



L₁ is 40 turns of No. 20 enameled copper wire wound on Ferroxcube P36/22-3B7 pot core or equivalent with 0.009 in. air gap.

Figure 22. Positive Switching Regulator

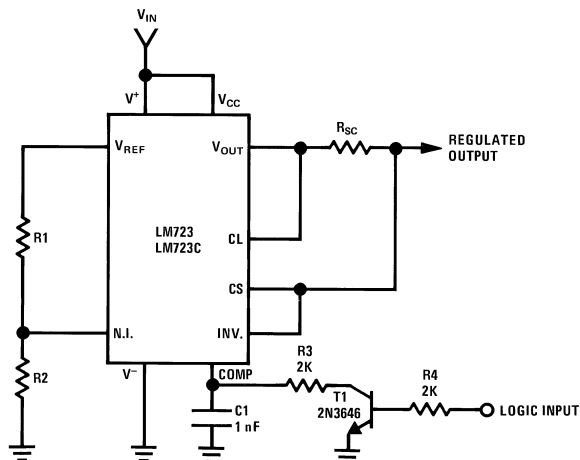
Typical Performance	
Regulated Output Voltage	+5V
Line Regulation ($\Delta V_{IN} = 30V$)	10 mV
Load Regulation ($\Delta I_L = 2A$)	80 mV



L_1 is 40 turns of No. 20 enameled copper wire wound on Ferroxcube P36/22-3B7 pot core or equivalent with 0.009 in. air gap.

Figure 23. Negative Switching Regulator

Typical Performance	
Regulated Output Voltage	-15V
Line Regulation ($\Delta V_{IN} = 20V$)	8 mV
Load Regulation ($\Delta I_L = 2A$)	6 mV



Note: Current limit transistor may be used for shutdown if current limiting is not required.

Figure 24. Remote Shutdown Regulator with Current Limiting

Typical Performance	
Regulated Output Voltage	+5V
Line Regulation ($\Delta V_{IN} = 3V$)	0.5 mV
Load Regulation ($\Delta I_L = 50 \text{ mA}$)	1.5 mV

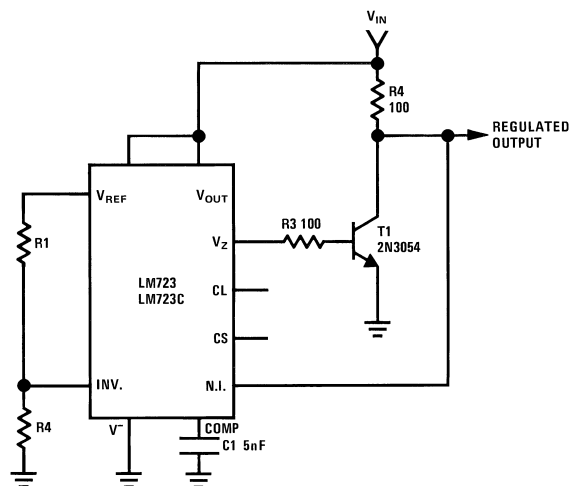
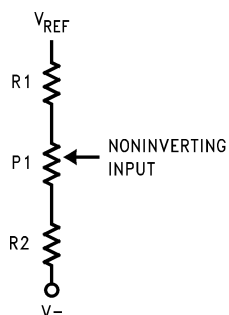


Figure 25. Shunt Regulator

Regulated Output Voltage	+5V
Line Regulation ($\Delta V_{IN} = 10V$)	0.5 mV
Load Regulation ($\Delta I_L = 100 \text{ mA}$)	1.5 mV



NOTE: Replace R1/R2 in figures with divider shown in [Figure 26](#)

Figure 26. Output Voltage Adjust

REVISION HISTORY SECTION

Date Released	Revision	Section	Originator	Changes
02/15/05	A	New Release, Corporate format	L. Lytle	1 MDS data sheet converted into one Corp. data sheet format. MJLM723-X, Rev. 1A0. MDS data sheet will be archived.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
JL723SCA	ACTIVE	CDIP	J	14	25	TBD	Call TI	Call TI	-55 to 125	JL723SCA JM38510/10201SCA Q	Samples
JL723SIA	ACTIVE	TO-100	LME	10	20	TBD	Call TI	Call TI	-55 to 125	JL723SIA JM38510/10201SIA Q ACO JM38510/10201SIA Q >T	Samples
JM38510/10201SCA	ACTIVE	CDIP	J	14	25	TBD	Call TI	Call TI	-55 to 125	JL723SCA JM38510/10201SCA Q	Samples
JM38510/10201SIA	ACTIVE	TO-100	LME	10	20	TBD	Call TI	Call TI	-55 to 125	JL723SIA JM38510/10201SIA Q ACO JM38510/10201SIA Q >T	Samples
M38510/10201SCA	ACTIVE	CDIP	J	14	25	TBD	Call TI	Call TI	-55 to 125	JL723SCA JM38510/10201SCA Q	Samples
M38510/10201SIA	ACTIVE	TO-100	LME	10	20	TBD	Call TI	Call TI	-55 to 125	JL723SIA JM38510/10201SIA Q ACO JM38510/10201SIA Q >T	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

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J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



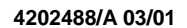
PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

METAL CYLINDRICAL PACKAGE



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